



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)

Shunpei YAMAZAKI)

Serial No. 09/619,477)

Filed: July 19, 2000)

For: CONTACT STRUCTURE AND
SEMICONDUCTOR DEVICE)

) Group Art Unit: 2813

) Examiner: E. Kielin

CERTIFICATE OF MAILING

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AMENDMENT AND RESPONSE TO ELECTION REQUIREMENT

Honorable Commissioner for Patents

Washington, D.C. 20231

Sir:

In response to the Office Action of October 9, 2002, please amend the subject
application as follows:

IN THE CLAIMS:

Please amend claims 1-2, 4-6, 8-11, 13-14, 17-20, 22, 24-26, 28-29, 31-32, 34,
36-38, 40-41, 43, 45, 47-49 and 51-52 as follows:

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1. (Amended) A contact structure comprising:
- a first substrate;
 - a second substrate;
 - a connecting wiring over said first substrate;
 - a wiring under said second substrate; and
 - an anisotropic conductive film between the first substrate and the second substrate,
- wherein said connecting wiring over said substrate and said wiring under said second substrate are electrically connected by said anisotropic conductive film,
- wherein said connecting wiring is a lamination film comprising a metallic film and a transparent conductive film in contact with said metallic film, and
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